



Please note that Cypress is an Infineon Technologies Company.

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

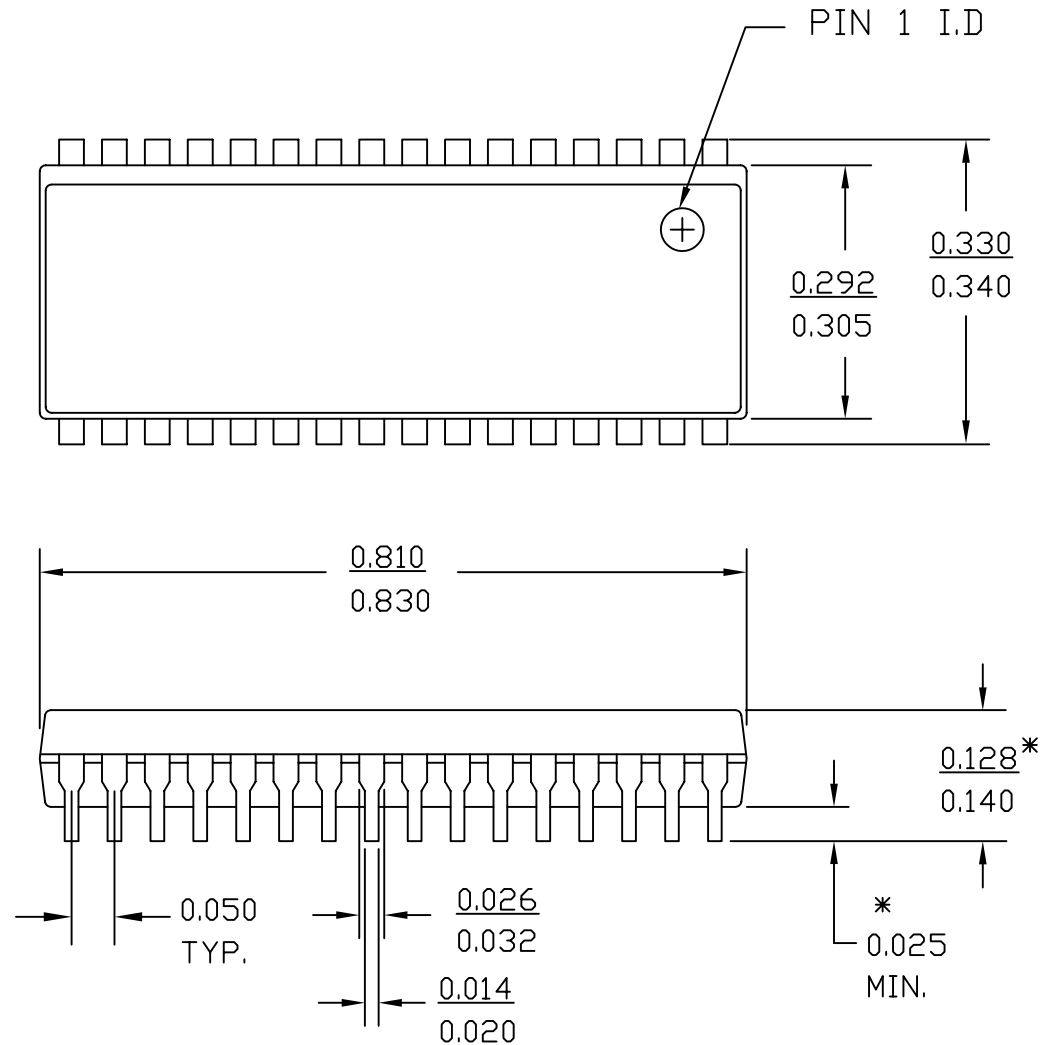
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

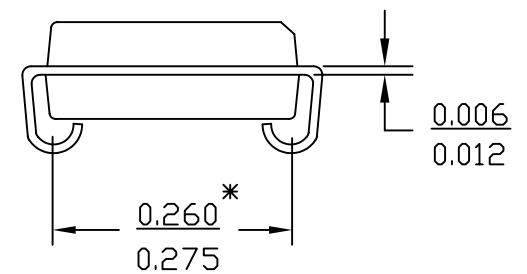
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

32 Lead (300 MIL) Molded SOJ



DIMENSIONS IN INCHES MIN.
MAX.
LEAD COPLANARITY 0.004 MAX.



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PACKAGE CODE(S)



TITLE PACKAGE OUTLINE, 32L SOJ 300 MILS V32.3
(CATALOG 32.3 MOLDED SOJ)

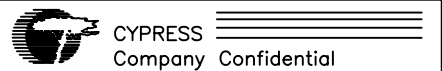
SPEC NO. 51-85041

REV *D

SCALE

SHEET 1 of 2

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	456	NEW RELEASE	12/10/92	N/A
1	-	*A	45899	CHG. DIM. AT *. ADD LEAD COPLANARITY	09/11/96	N/A
1	-	*B	2871406	Changed template, & title from CATALOG 32.3 MOLDED SOJ to PACKAGE OUTLINE, 32L SOJ 300 MILS V32.3 (CATALOG 32.3 MOLDED SOJ)	02/02/10	QAD
1	-	*C	3391734	Sunset review no change	10/01/11	QAD
1	-	*D	4538860	Sunset Review, Changed Drawing Template.	10/15/14	QAD



TITLE PACKAGE OUTLINE, 32L SOJ 300 MILS V32.3
(CATALOG 32.3 MOLDED SOJ)

SPEC NO. 51-85041 REV *D

SCALE SHEET 2 OF 2

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PACKAGE CODE(S)